VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE ABSTRACT:

Please amend the Abstract to read as follows:

[The present invention aims to provide a wiring substrate highly reliable in insulation and connection and a method for manufacturing the wiring substrate.] [The] A wiring substrate [comprises] having two or more wiring layers, insulation layers interposed between the neighboring wiring layers and containing an organic resin, and a via formed in the insulation layers and extended between neighboring wiring layers. The via [contain] including functional substances, as well as some of the voids (first voids] where at least the organic resins from the insulation layers exist and the remaining voids (second voids) where a gas exists. [Consequently, so-called paste bleed, which is penetration of an insulation layer with a conductive paste, does not takes place and the elasticity modulus in the entire via becomes low and the flexibility is improved attributed to the second voids in the via. The expansion and the contraction well respond to the mechanical stress applied to the wiring substrate and thus disconnected of wiring layers hardly takes place and the reliability of electric and mechanical connection between the wiring layers is heightened.]

IN THE CLAIMS:

Please cancel claim 2.

Please amend claims 1, 3, 6, 14 and 25-28 as follows:

1. (Amended) A wiring substrate comprising:

two or more wiring layers;

insulation layers interposed between said neighboring wiring layers [and containing an organic resin]; and

a via formed in the insulation layers so as to connect said wiring layers to one another,

wherein said via is characterized in containing a plurality of functional substances while keeping voids in the surroundings, and

wherein the voids include first voids where at least the organic resins from the insulation layer exist and second voids where a gas exists, said second voids are selectively formed in the portions where the agglomerated functional substances exist.

3. (Amended) The wiring substrate as claimed in claim [2] 1, characterized in that said second voids have a smaller average volume than the average volume of a plurality of the respective functional substances forming at least the agglomeration portions among the functional substances.

6. (Amended) A wiring substrate comprising:

two or more wiring layers;

insulation layers interposed between said neighboring wiring layers; and

a via formed in the insulating layers so as to connect said wiring layers to one another,

wherein each of said insulation layers [comprise films] comprises an insulating

substrate and at least one adhesive [layers] layer containing adhesives [and formed at least one side], said at least one adhesive layer formed on a first surface of said insulating substrate, said first surface being one of an upper surface or a lower surface of said insulating substrate, and

wherein said via [contain] contains functional substances and the adhesives of said adhesive [layers] layer penetrating and existing in the voids in the surroundings of the functional substances.

14. (Amended) A method for manufacturing a wiring substrate comprising:

a first process of forming [via] vias in which voids are formed by filling functional substances in via holes formed in an [insulation substrate of a film bearing an adhesive layer containing adhesives in at least one side] insulation layer, said insulating layer comprising an insulating substrate and at least one adhesive layer formed on a first surface of said insulating substrate, said first surface being one of an upper surface or a lower surface of said insulating substrate; and

a second process of penetrating the voids of said via hole with the adhesive of said adhesive layer.

25. (Twice Amended) The method for manufacturing a wiring substrate as claimed in claim 11, characterized in that said vias operate to couple metal conductors to one another, said metal conductors comprising [are] either metal foils or wiring patterns.

26. (Amended) The method for manufacturing a wiring substrate as claimed in claim 12, characterized in that said vias operate to couple metal conductors to one another, said metal conductors comprising [are] either metal foils or wiring patterns.

27. (Amended) The method for manufacturing a wiring substrate as claimed in claim 13, characterized in that said vias operate to couple metal conductors to one another, said metal conductors comprising [are] either metal foils or wiring patterns.

28. (Amended) The method for manufacturing a wiring substrate as claimed in claim 14, characterized in that said vias operate to couple metal conductors to one another, said metal conductors comprising [are] either metal foils or wiring patterns.